	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1694912	chip or die or dice or ic or package or packaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	2624593	encapsulat$6 or resin or epoxy or thermoplastic$4 or thermoresin or mold$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L4	4751447	vertical$4 or verticl$4 or "90" near2 (deg or degree) or inclin$4 or ang|$4 or tip$4 or slop$4 or acut$4 or obtus$4 or theta or phi or alpha or beta	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L5	22273	1 same 2 same 3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	IS&R	L6	1249	((438/124) or (438/126) or (438/973)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
6	BRS	L7	10083	1 near4 2 same 3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L8	3114	1 near4 2 same 3 and (semiconductor or si or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L9	1068	1 near4 2 near10 3 and (semiconductor or si or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L10	145296	438/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L11	263898	257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L#	Hits	Search Text	DBs
11	BRS	L1 2	535	9 and (10 or 11)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	L1 3	369	12 and (@ad < "20000901")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	L1 4	699	9 not 13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	L1 5	411	14 and (@ad < "20000901")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB